

TECHNICAL SPEC FOR CMP tool

**System Model:
Cybeq 8000**

Process: Oxide

Substrate size: 6 inch

Wet stage loaders: Wafer loading module, custom designed load and unload system containing 4 cassette nests and 2 Cybeq articulated robots

Chemicals / gases used: Klebosol & DI water

Polisher controller: head speed controller SC400 servocontroller

Platen assemblies: 36" diameter, 304stainless steel with coating. Platen & carrousel controller SC750series

Pad conditioner assemblies: pad dresser

Slurry distribution motors and arm assemblies: ASSY 0162-5088 slurry pump drive/head

Polishing heads: 6 floating head wafer carriers

Head cleaning loading and unloading unit (HCLU):

Loaders: wafer handling up to 200mm in diameter, 2 Cybeq 8000robots & 2 head loading modules (HLM)

Robot assembly: Cybeq 8000robot

Computer rack: Siemens PLCs for motion control

Metrology tools: NA

SW:

Missing parts: none

Defected parts:

Operating system: MS windows - GUI